



Mini-Circuits

THIN FILM SURFACE MOUNT

Low Pass Filter

ALF-7300+

50Ω

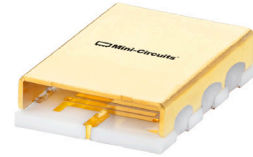
DC to 7.3 GHz

KEY FEATURES

- Low Passband Insertion Loss of 0.7 dB Typ.
- High Rejection of 39 dB Typ.
- Good Return Loss of 15 dB Typ.
- Small Size, 5.59 x 8.13 x 2.03 mm

APPLICATIONS

- Wi-Fi 6E
- Test and Measurement Equipment

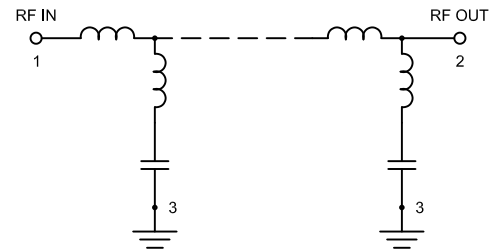


Generic photo used for illustration purposes only

PRODUCT OVERVIEW

Mini-Circuits' Surface Mount Thin-Film filters offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance. Low pass, high pass, and bandpass surface mount thin-film designs can be realized with this technology up to 40 GHz in a small form factor helping customers achieve their SWaP objectives. Using our high quality thin-film manufacturing process we can guarantee repeatability on large batches of filters.

FUNCTIONAL DIAGRAM

ELECTRICAL SPECIFICATIONS^{1,2,3} AT +25°C

Parameter		F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Passband	Insertion Loss	DC-F1	DC - 7.3	—	0.7	1.6	dB
	Freq. Cut-Off ⁴	Fc	8.2	—	3	—	dB
	Return Loss	DC-F1	DC - 7.3	—	15	—	dB
Stopband	Rejection	F2-F3	9.4 - 10	25	37	—	dB
		F3-F4	10 - 16	33	39	—	
		F4-F5	16 - 18	—	20	—	

1. Tested in Evaluation Board P/N TB-ALF-7300+ with feedline losses removed by normalization of S12 and S21 traces to measurement of TB thru-line.

2. This filter is bi-directional RF1 and RF2 ports may be interchanged, see S-Parameters for actual performance.

3. This filter can handle a DC of 100 mA.

4. Typical variation ±3%

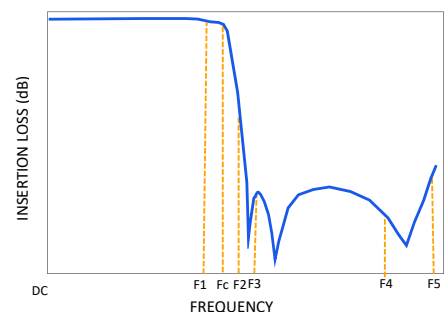
ABSOLUTE MAXIMUM RATINGS⁵

Parameter	Ratings
Operating Temperature	-55 °C to +125 °C
Storage Temperature	-55 °C to +125 °C
Input Power ⁶	10.75 W Max. at 25°C

5. Permanent damage may occur if any of these limits are exceeded.

6. Power rating applies only to signals within the passband. Derated power at +125°C is 5.2 W.

TYPICAL FREQUENCY RESPONSE



Mini-Circuits

www.minicircuits.com P.O. Box 350166, Brooklyn, NY 11235-0003 (718) 934-4500 sales@minicircuits.com

REV. OR
ECO-024893
ALF-7300+
EDU4856
URJ
250318

PAGE 1 OF 6



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THIN FILM SURFACE MOUNT

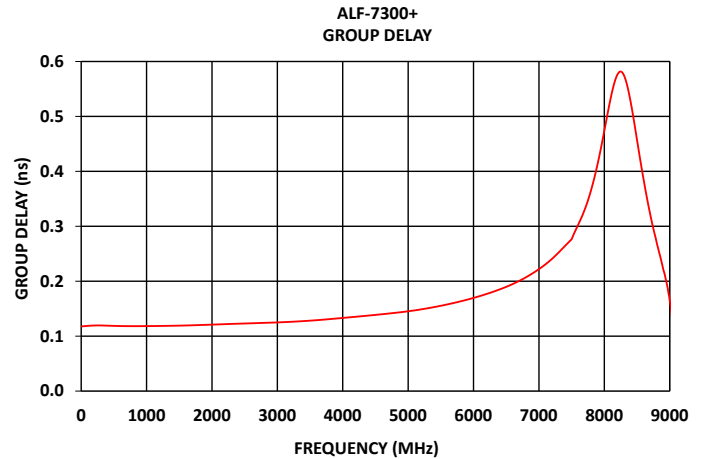
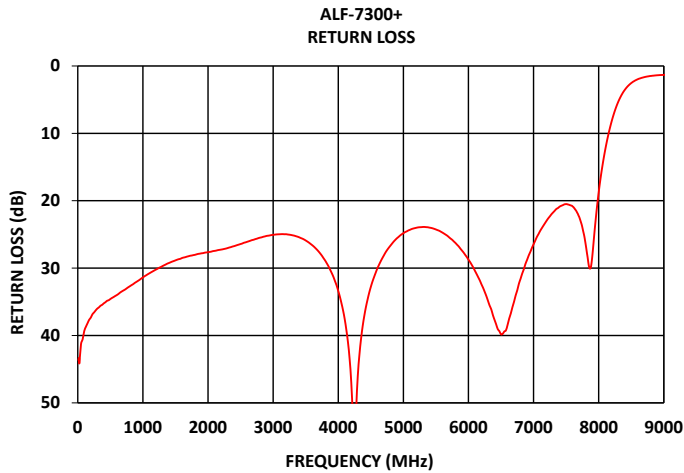
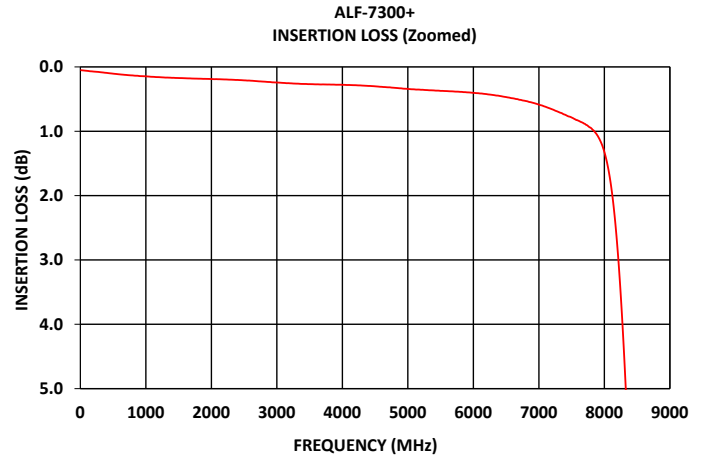
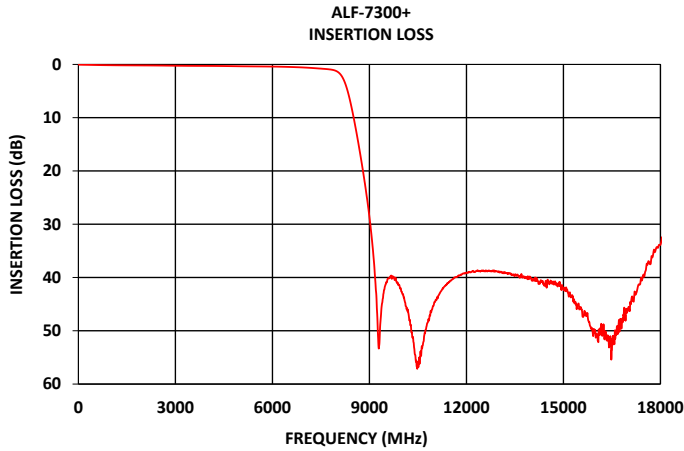
Low Pass Filter

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DC to 7.3 GHz

TYPICAL PERFORMANCE GRAPHS AT +25°C





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PAD DESCRIPTION

Function	Pad Number	Description
RF1 ²	1	Connects to RF Input Port
RF2 ²	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-764)
NC	—	No connection, not used internally. See drawing PL-764 for connection to PCB

TOP VIEW

INDEX

220 [5.59]

1

0

2

320 [8.13]

PCB LAND PATTERN

.110 [2.79]

220 [5.59]

0

Ø.014 [Ø0.36]

R.013 [R0.33]

320 [8.13]

SUGGESTED LAYOUT TOLERANCE TO BE WITHIN: ±.002

WEIGHT: 0.2 grams

DIMENSIONS ARE IN INCHES [MM]. TOLERANCES: 2 PL.±.01; 3 PL.±.005

METALLIZATION

BOTTOM VIEW

.007 [0.18]

.013 [0.33]

.110 [2.79]

.014 [0.36]

3

2

.026 [0.65]

1

Figure 1 is a technical drawing of a 100-pin BGA package layout. It shows a square package with a central square area containing a grid of pins. The overall width is 320, and the central area width is 294. The pin pitch is 0.10. The package outline is shown with a dashed line. The central area is labeled 'INDEX' and 'PIN 1'. The package outline is labeled 'PACKAGE OUTLINE'. The central area is labeled '4x.013±.0005 SPACE WIDTH' and '2x.015±.0005 TRACE WIDTH'.

1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B Lo Pro) WITH DIELECTRIC THICKNESS .0073x.0007. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

 DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)

 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

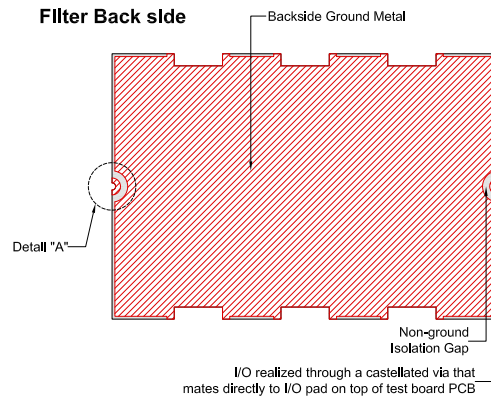
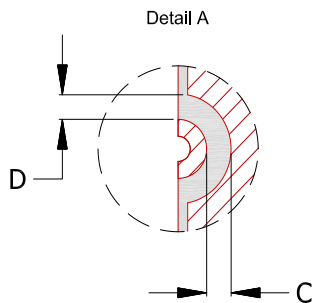
PRODUCT MARKING*: ALF-7300

*Marking may contain other features or characters for internal lot control.

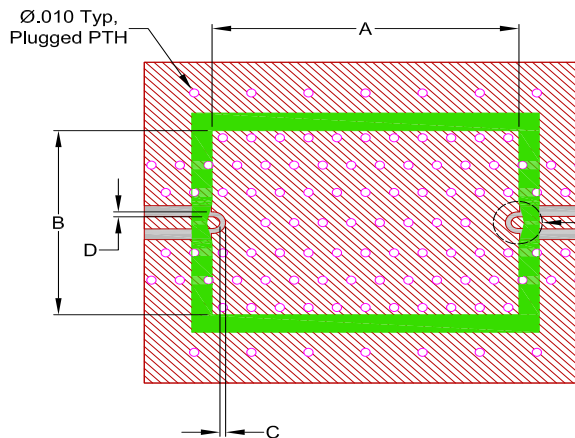




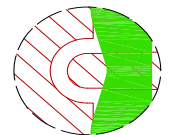
RECOMMENDED PCB LAYOUT PATTERN FOR FILTER

Filter RF I/O Detail
(Filter Back Side)

PCB Pattern Recommendations



DETAIL "B"

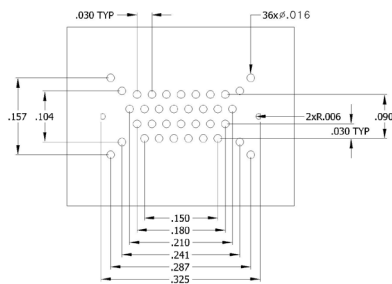
SEE
DETAIL "B"

- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use Solder mask at Customer PCB at outer area of filter pattern/ footprint with a clearance of about 1.25mil at each side. (Tighter registration tolerance required for solder mask)
- 5) Recommended to use Solder mask at I/O of Customer PCB as per above diagram (refer detail B).

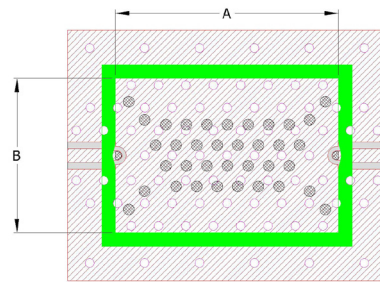
**COMMENTS ON COMPONENT HANDLING AND SOLDER ATTACH**

- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Stencil opening drawing



Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- 5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.



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DC to 7.3 GHz

ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASH BOARD.

[CLICK HERE](#)

Performance Data and Graphs	Data
	Graphs
	S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	UC2731 Lead Finish: Gold over Nickel Plate.
RoHS Status	Compliant
Tape and Reel	TR-F003
Suggested Layout for PCB Design	PL-764
Evaluation Board	TB-ALF-7300+
	Gerber File
Environmental Rating	ENV120

NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html



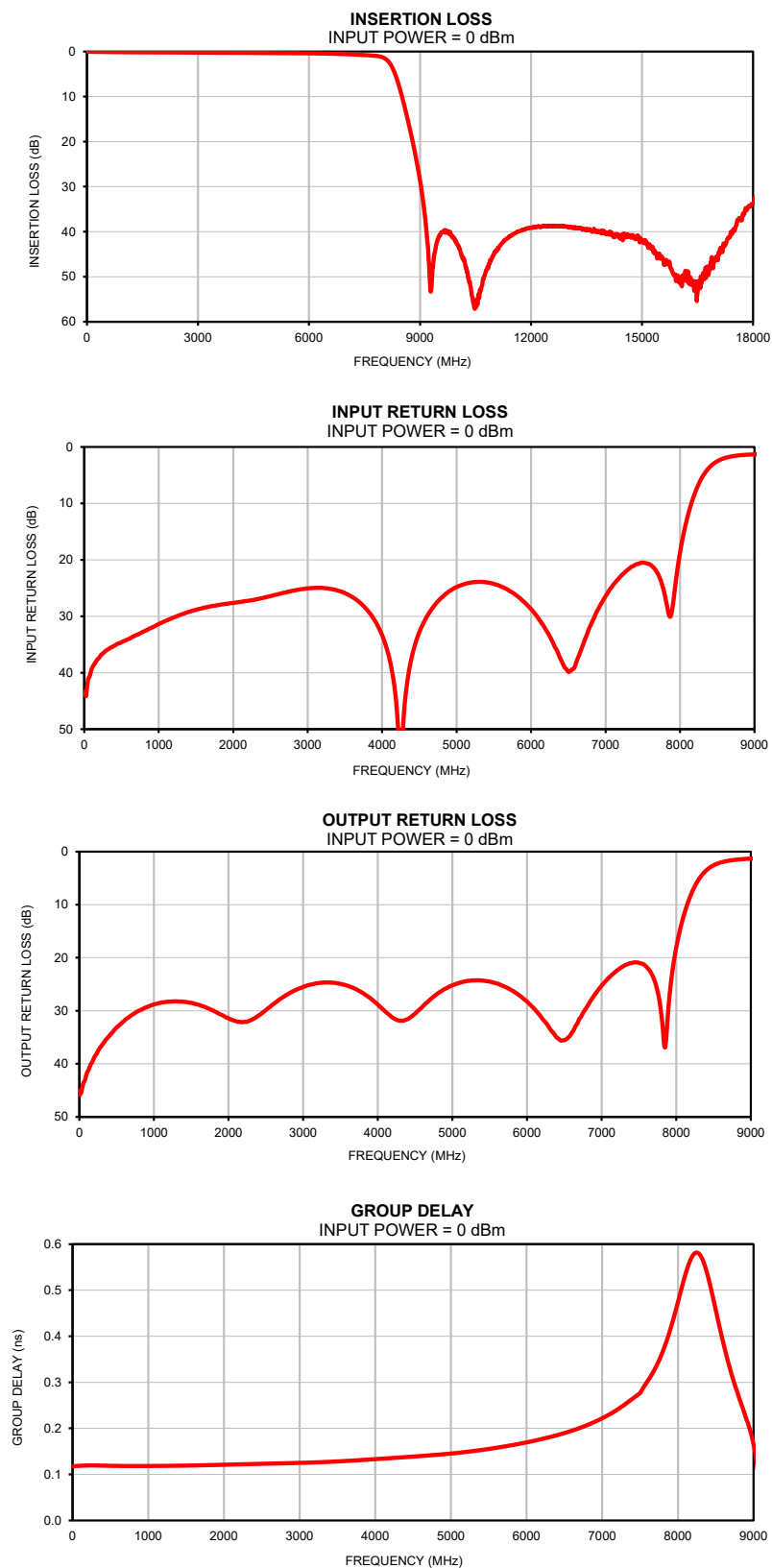
Thin-Film Lowpass Filter

ALF-7300+

Typical Performance Data

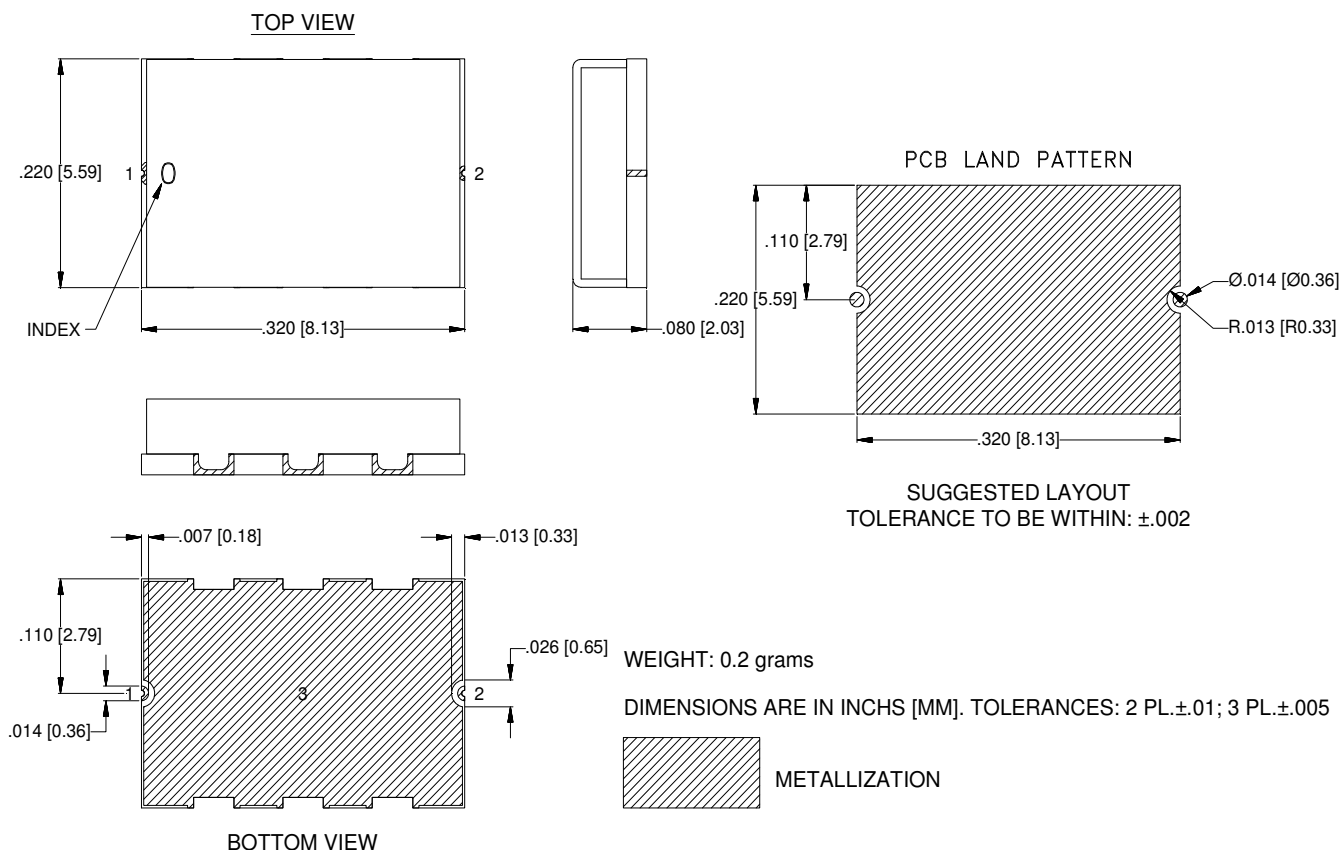
FREQ.	Insertion Loss	Input Return Loss	Output Return Loss	FREQ.	Group Delay
(MHz)	(dB)	(dB)	(dB)	(MHz)	(ns)
10	0.05	43.66	45.83	10	0.12
20	0.05	43.33	44.90	20	0.12
50	0.06	41.27	43.73	25	0.12
100	0.06	39.32	41.75	50	0.12
150	0.07	38.18	40.14	75	0.12
200	0.07	37.35	38.75	100	0.12
250	0.08	36.58	37.56	125	0.12
300	0.08	36.01	36.54	150	0.12
350	0.09	35.58	35.55	175	0.12
400	0.09	35.22	34.74	200	0.12
450	0.10	34.85	33.95	225	0.12
500	0.10	34.59	33.16	250	0.12
550	0.11	34.29	32.53	300	0.12
600	0.12	34.00	31.89	400	0.12
700	0.12	33.33	30.81	500	0.12
800	0.13	32.69	29.97	600	0.12
900	0.14	32.05	29.34	700	0.12
1000	0.15	31.39	28.79	800	0.12
1100	0.15	30.77	28.45	900	0.12
1200	0.16	30.22	28.29	1000	0.12
1500	0.17	28.85	28.50	1100	0.12
2000	0.19	27.64	31.41	1200	0.12
2500	0.21	26.43	29.86	1300	0.12
3000	0.24	25.06	25.49	1400	0.12
3500	0.27	25.90	24.92	1500	0.12
4000	0.28	33.37	28.82	1600	0.12
5000	0.34	24.83	25.19	1700	0.12
6000	0.40	28.75	28.25	1800	0.12
6500	0.47	39.83	35.54	1900	0.12
7000	0.59	26.46	25.27	2000	0.12
7100	0.62	24.49	23.73	2100	0.12
7300	0.70	21.74	21.54	2200	0.12
7500	0.79	20.50	20.95	2300	0.12
7700	0.88	22.39	23.96	2400	0.12
7900	1.07	28.39	28.70	2500	0.12
8000	1.32	18.74	18.08	2600	0.12
8100	1.84	12.44	12.09	2700	0.12
8200	2.82	8.17	8.01	2800	0.12
8250	3.55	6.59	6.50	2900	0.12
8500	9.60	2.53	2.58	3000	0.13
8700	16.27	1.66	1.71	3100	0.13
9000	28.62	1.32	1.31	3200	0.13
9400	44.64	1.26	1.08	3300	0.13
9500	41.25	1.26	1.03	3400	0.13
10000	42.63	1.27	0.91	3500	0.13
10500	55.79	1.25	0.91	3600	0.13
11000	44.85	1.19	1.01	3700	0.13
11600	40.20	1.09	1.15	3800	0.13
12000	39.12	1.05	1.22	3900	0.13
12500	38.76	1.04	1.27	4000	0.13
13000	38.83	1.10	1.22	4500	0.14
13500	39.42	1.21	1.14	5000	0.15
14000	40.21	1.36	1.03	5500	0.16
14400	41.51	1.49	0.97	6000	0.17
15000	42.14	1.64	0.96	6200	0.18
15500	45.82	1.69	1.03	6500	0.19
16000	51.30	1.63	1.15	7000	0.22
17000	46.10	1.34	1.51	7100	0.23
17500	39.84	1.22	1.65	7200	0.24
18000	33.88	1.16	1.70	7300	0.25

Typical Performance Curves



Outline Dimensions

UC2731

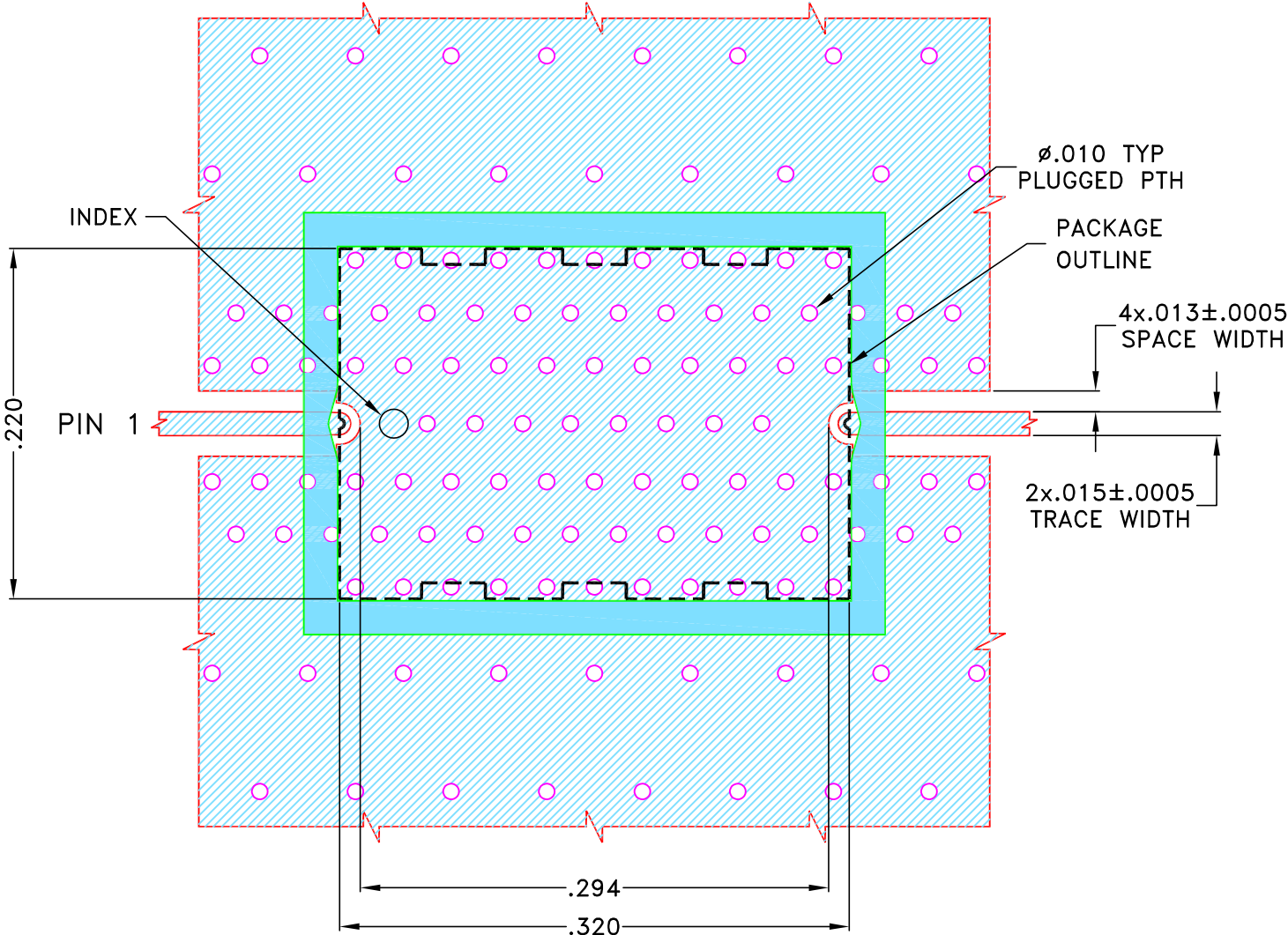


Notes:

1. Case material: Gold over Nickel over Annealed Stainless Steel.
2. Base: Ceramic
3. Termination finish: **as shown below or indicated on Data Sheet.**
For RoHS Case Styles: Gold over Nickel plate. All models, (+) suffix.

THIRD ANGLE PROJECTION		REVISIONS				
	REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
	OR	NP0-003903	NEW RELEASE	OCT 23	LK	VC

SUGGESTED MOUNTING CONFIGURATION
FOR UC2731 CASE STYLE



NOTES:

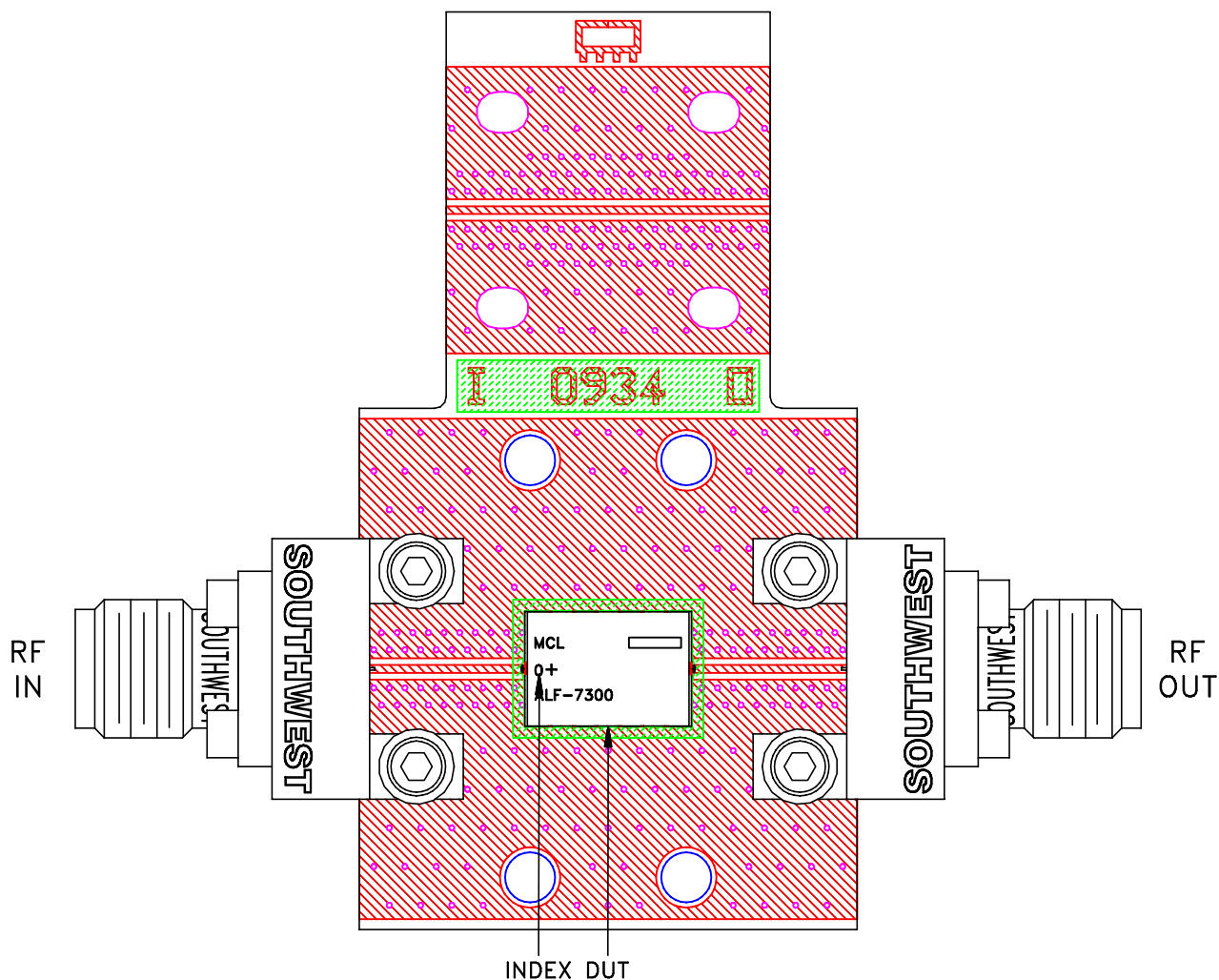
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FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

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 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

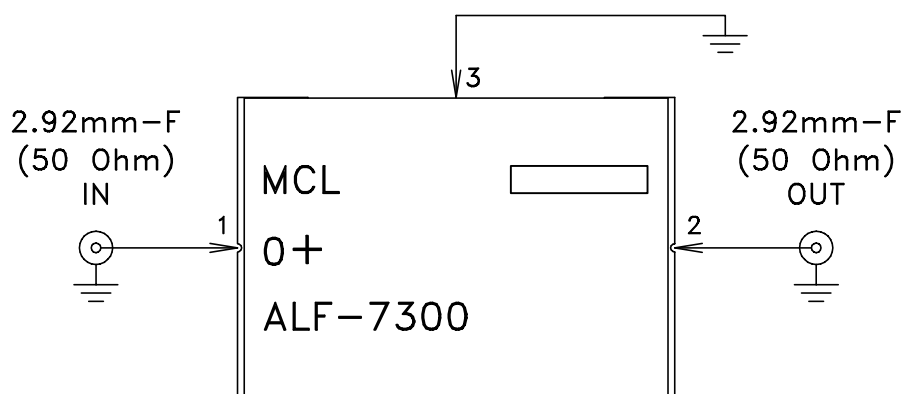
UNLESS OTHERWISE SPECIFIED		INITIALS		DATE		Mini-Circuits® 13 Neptune Avenue Brooklyn NY 11235					
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS ± 3 PL DECIMALS ± .005 ANGLES ± FRACTIONS ± 		DRAWN	LK	09 OCT 23							
		CHECKED	MD	09 OCT 23							
		APPROVED	RR	13 OCT 23							
						PL DWG, UC2731 C.S, 50 OHM, ALF					
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						FILE: 98-PL-764		SCALE: 9.1:1	SHEET: 1 OF 1		
						ASHEETA1.DWG REV:A DATE:01/12/95					

Evaluation Board and Circuit

TB-ALF-7300+



Schematic diagram



Notes:

1. PCB Material: ROGERS (R04350B Lo Pro) OR Equivalent, Dielectric Constant= $3.48 \pm .05$
Dielectric Thickness: $.0073 \pm .0007$ inch
2. 50 Ohm 2.92mm Female Connectors.

 **Mini-Circuits®**



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Thermal Shock	-55° to 125°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, Except +125°C